

**Fifteenth Ieee/Chmt International Electronics
Manufacturing Technology Symposium: October 4-6,
1993 Santa Clara, Ca USA (Ieee/Cpmt International
Electronics Manufacturing Technology Symposium)
By Albert Blodgett**

Chandrasekhar (Spike) Narayan - Publications -

San Jose, CA, USA +1 408 927 2405. Annual International Reliability Physics Symposium, Phoenix for CMOS BEOL Interconnect Technology C. Narayan
http://researcher.watson.ibm.com/researcher/view_pubs.php?person=us-narayanc&t=1

Patent US8247907 - Methods for forming -

Methods for forming interconnects in microelectronic workpieces and microelectronic workpieces formed using such methods are disclosed herein. One embodiment, for
<http://www.google.com/patents/US8247907>

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<http://www.amazon.com/Fifteenth-International-Electronics-Manufacturing-Technology/dp/0780314255>

820 Lumia Manual: All the Time in the World, -

All the Time in the World; Fifteenth IEEE/CHMT International Electronics Manufacturing Technology Symposium

<http://www.tayomedia.com/category/820-lumia-manual/>

The Mechanics of Molded Plastic Packages - -

The Mechanics of Molded Plastic Proc. International Electronics Manufacturing Symp. IEEE-CHMT Proc. International Electronics Manufacturing

<http://link.springer.com/article/10.1007/BF03258169>

Proceedings of 15th IEEE/ CHMT International -

Proceedings of 15th IEEE/CHMT International Electronic Manufacturing Technology Symposium Full Text as Electronic Manufacturing Technology Symposium,

<http://ieeexplore.ieee.org/xpl/articleDetails.jsp?reload=true&arnumber=398232&contentType=Conference+Publications>

IEEE- CHMT Fifteenth International Electronics -

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<http://www.barnesandnoble.com/w/ieee-chmt-fifteenth-international-electronics-manufacturing-technology-symposium-1993-ieee-components-hybrids-and-manufacturing-technology/1015126698?ean=9780780314252>

A Survey of Test Techniques for MCM Substrates - -

of the Eleventh IEEE/CHMT International Electronics Eleventh IEEE/CHMT International Electronics Manufacturing A Survey of Test Techniques for

<http://link.springer.com/article/10.1023/A%3A1008214330042>

IEEE Xplore - Conference Table of Contents -

Previous Titles. Electronic Manufacturing Technology Symposium, 1993, Fifteenth IEEE/CHMT International; Electronic Manufacturing Technology Symposium, 1992.

http://ieeexplore.ieee.org/xpl/mostRecentIssue.jsp?punumber=3174&sortType%3Dasc_p_Sequence%26filter%3DAND%28p_IS_Number%3A8999%29&pageNumber=3

Patent US7829976 - Microelectronic devices and -

Microelectronic devices, methods for packaging microelectronic devices, and methods for forming interconnects in microelectronic devices are disclosed herein. In one

<http://www.google.com/patents/US7829976>

Patent US7863187 - Microfeature workpieces and -

Methods for forming interconnects in microfeature workpieces, and microfeature workpieces having such interconnects are disclosed herein. The microfeature workpieces

<http://www.google.com/patents/US7863187>

IEEE/ CHMT International Electronic Manufacturing -

Uniform Title IEEE/CHMT International Electronic Manufacturing Technology Symposium (1988) Meeting IEEE/CHMT International Electronic Manufacturing Technology Symposium.

<http://searchworks.stanford.edu/view/2007617>

Patent US7915736 - Microfeature workpieces and -

Methods for forming interconnects in microfeature workpieces, and microfeature workpieces having such interconnects are disclosed herein. In one embodiment, a method

<http://www.google.com/patents/US7915736>

Patent US7622377 - Microfeature workpiece -

Microfeature workpiece substrates having through-substrate vias, and associated methods of formation are disclosed. A method in accordance with one embodiment for

<http://www.google.com/patents/US7622377>

Patent US7589008 - Methods for forming -

One aspect of the invention is directed toward a method for manufacturing a microelectronic workpiece having a plurality of microelectronic dies.

<http://www.google.com/patents/US7589008>

Fifteenth IEEE/ CHMT International Electronics -

Fifteenth IEEE/CHMT International Electronics Manufacturing Technology Symposium : electronics manufacturing for the year 2000 : October 4-6, 1993, Santa Clara, CA, USA

<http://www.worldcat.org/title/fifteenth-ieeechmt-international-electronics-manufacturing-technology-symposium-electronics-manufacturing-for-the-year-2000-october-4-6-1993-santa-clara-ca-usa/oclc/29617026>

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<https://www.linkedin.com/in/newcombe>

Patent US9001486 - Internally overlapped -

The application discloses novel internal structures of energy conditioners, assemblies of external structures of energy conditioners and mounting structure, and novel

<http://www.google.com/patents/US9001486>

FabTime's Wafer Fab Cycle Time Bibliography -

International Electronics Manufacturing Cycle Time Manufacturing 1993 IEEE/CHMT International

<http://www.fabtime.com/CTBiblio.shtml>

Intelligent manufacturing systems (Smart -

The Smart Mechatronics/Intelligent Manufacturing Research initiative at Louisiana State University 15th IEEE /EIA Components (CHMT) International Electronics

<http://www.sciencedirect.com/science/article/pii/095741589500049B>

Patent US7749899 - Microelectronic workpieces and -

Methods and systems for forming electrical interconnects through microelectronic workpieces are disclosed herein. One aspect of the invention is directed to a method

<http://www.google.com/patents/US7749899>

IEEE Components, Packaging, and Manufacturing -

IEEE Components, Packaging, And Manufacturing Technology 2015 16th International Conference on Electronic 2016 15th IEEE Intersociety Conference on

<http://cpmt.ieee.org/>

Adhesive strength - IEEE Conferences, -

M. Electronic Manufacturing Fifth IEEE/CHMT International, and electronic packaging. Poor adhesive strength and weakness in terms of impact

<http://technav.ieee.org/tag/4944/adhesive-strength>

International Electronics Manufacturing -

International Electronics Manufacturing Technology Symposium, 1993
Proceedings of Japan IEMT/14th IEEE/CHMT International. 9-11 June, 1993;
Kanazawa, Japan.

<http://www.amazon.com/International-Electronics-Manufacturing-Proceedings-International/dp/0780314336>

Generic Interface Builder - Patent 6708074 by -

invention relates generally to manufacturing automation and specifically to software for automation of semiconductor manufacturing of Santa Clara,

<http://www.docstoc.com/docs/52636273/Generic-Interface-Builder---Patent-6708074>

Patent US8536485 - Systems and methods for forming -

Systems and methods for forming apertures in microfeature workpieces are disclosed herein. In one embodiment, a method includes directing a laser beam toward a

<http://www.google.com/patents/US8536485>

Patent US8748311 - Microelectronic devices and -

Microelectronic devices and methods for filling vias and forming conductive interconnects in microfeature workpieces and dies are disclosed herein. In one embodiment

<http://www.google.com/patents/US8748311>

T. Weller -

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<https://www.infona.pl/contributor/1@bwmeta1.element.elsevier-31b38170-dba0-3165-8616-ced7e7eef532/tab/publications>

Patent US7531453 - Microelectronic devices and -

Microelectronic devices, methods for packaging microelectronic devices, and methods for forming interconnects in microelectronic devices are disclosed herein.

<http://www.google.com/patents/US7531453>

0780314336 - International Electronics -

International Electronics Manufacturing Technology Symposium, 1993
Proceedings of Japan IEMT/14th IEEE/CHMT International. 9-11 June, 1993;
Kanazawa, Japan.

<http://www.abebooks.com/book-search/isbn/0780314336/>

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<http://www.amazon.it/Fifteenth-International-Electronics-Manufacturing-Technology/dp/0780314255>

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